

# FRED

## Ultrafast Soft Recovery Diode, 2 x 15 A

#### **FEATURES**

- Ultrafast recovery
- Ultrasoft recovery
- Very low I<sub>RRM</sub>
- Very low Qrr
- Specified at operating conditions
- Designed and qualified for industrial level

#### BENEFITS

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

#### DESCRIPTION

HFA30PA60C is a state of the art center tap ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600V and 15A per leg continuous current, the HFA30PA60C is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the FRED product line features extremely low values of peak recovery current (IRRM) and does not exhibit any tendency to "snap-off" during the tb portion of recovery. The FRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These FRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The FRED HFA30PA60C is ideally suited for applications in power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.







PRODUCT SUMMARY				
V <sub>R</sub>	600 V			
V <sub>F</sub> at 15A at 25 °C	1.7 V			
I <sub>F(AV)</sub>	2 x 15 A			
t <sub>rr</sub> (typical)	19 ns			
T <sub>J</sub> (maximum)	150 °C			
Q <sub>rr</sub> (typical)	80 nC			
dl <sub>(rec)M</sub> /dt (typical)	160 A/µs			
I <sub>RRM</sub> (typical)	4.0 A			

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS			
Cathode to anode voltage	V <sub>R</sub>		600	V			
Maximum continuous forward current		T <sub>C</sub> = 100 °C	15				
per device	I <sub>F</sub>		30	A			
Single pulse forward current	I <sub>FSM</sub>		150				
Maximum repetitive forward current	I <sub>FRM</sub>		60				
Movimum nouser discipation	PD	T <sub>C</sub> = 25 °C	74	w			
Maximum power dissipation	гD	T <sub>C</sub> = 100 °C	29	VV V			
Operating junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		- 55 to + 150	°C			



ELECTRICAL SPECIFICA	ATIONS	G (T <sub>J</sub> = 25 °C unless otherwise specified)				
PARAMETER	SYMBOL	TEST CONDITIONS	MIN. TYP. M		MAX.	UNITS
Cathode to anode breakdown voltage	V <sub>BR</sub>	I <sub>R</sub> = 100 μA	600	-	-	
Maximum forward voltage	V <sub>FM</sub>	I <sub>F</sub> = 15 A	-	1.55	1.7	V
		I <sub>F</sub> = 30 A	-	1.80	2.0	
		I <sub>F</sub> = 15 A, T <sub>J</sub> = 125 °C	-	1.40	1.55	
Maximum reverse Ieakage current	$V_R = V_R$ rated	-	1.0	10		
	'RM	$T_J = 125^{\circ}C, V_R = V_R rated$	-	400	1000	μA
Junction capacitance	CT	V <sub>R</sub> = 200V		25	50	pF
Series inductance	L <sub>S</sub>	Measured lead to lead 5 mm from package body	-	12	-	nH

DYNAMIC RECOVERY CHARACTERISTICS PERLEG (T <sub>J</sub> = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS			TYP.	MAX.	UNITS
Reverse recovery time	+	I <sub>F</sub> = 0.5A, I <sub>R</sub> = 1.0A, I <sub>RR</sub> = 250mA (RG#1 CKT)		-	25	33	ns
	t <sub>rr</sub>	$I_F$ = 1.0 A, dI <sub>F</sub> /dt = -200 A/µs, V <sub>R</sub> =30 V, T <sub>J</sub> = 25°C		-	19	-	
	t <sub>rr1</sub>	T <sub>J</sub> = 25 °C	I <sub>F</sub> = 15A dI <sub>F</sub> /dt = -200 A/μs V <sub>R</sub> = 200 V	-	42	60	- A
	t <sub>rr2</sub>	T <sub>J</sub> = 125 °C		-	70	120	
Peak recovery current	I <sub>RRM1</sub>	T <sub>J</sub> = 25 °C		-	4.0	6.0	
	I <sub>RRM2</sub>	T <sub>J</sub> = 125 °C		-	6.5	10	
Reverse recovery charge	Q <sub>rr1</sub>	T <sub>J</sub> = 25 °C		-	80	180	nC
	Q <sub>rr2</sub>	T <sub>J</sub> = 125 °C		-	220	600	
Peak rate of fall of recovery current during $\boldsymbol{t}_{b}$	dl <sub>(rec)M</sub> /dt1	T <sub>J</sub> = 25 °C		-	250	-	A/µs
	dl <sub>(rec)M</sub> /dt2	T <sub>J</sub> = 125 °C		-	160	-	πµs

THERMAL - MECHANICAL SPECIFICATIONS PER LEG							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Lead temperature	T <sub>lead</sub>	0.063" from case (1.6 mm) for 10 s	-	-	300	°C	
Junction to case, single leg conduction	P		-	-	1.7		
Junction to case, both legs conducting	R <sub>thJC</sub>		-	-	0.85		
Thermal resistance, junction to ambient	R <sub>thJA</sub>	Typical socket mount	-	-	40	K/W	
Thermal resistance, case to heatsink	R <sub>thCS</sub>	Mounting surface, flat, smooth and greased	-	0.25	-		
Weight			-	6.0	-	g	
			-	0.21	-	oz.	
Mounting torque			6.0 (5.0)	-	12 (10)	kgf . cm (lbf . in)	
Marking device		Case style TO-247AB (JEDEC)	HFA30PA60C				





#### Fig.1 Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)

10000 = 150° Γı Reverse Current - I<sub>R</sub> (µA) 1000 100 = 125 °C 10 1 0.1 25°C 0.01 100 300 0 200 400 500 600 Reverse Voltage - V<sub>R</sub> (V)

Fig.2 Typical Reverse Current vs. Reverse Voltage (Per Leg)

Fig.3 Typical Junction Capacitance vs. Reverse Voltage (Per Leg)



#### Fig.4 Maximum Thermal Impedance Z<sub>thJC</sub> Characteristics (Per Leg)



t1, Rectangular Pulse Duration (sec)





Fig.5 Typical Reverse Recovery Time vs. dl<sub>F</sub>/dt (Per Leg)

Fig.6 Typical Recovery Current vs. dI<sub>F</sub>/dt (Per Leg)



 $\begin{array}{c} V_{R} = 200V \\ T_{J} = 125^{\circ}C \\ T_{J} = 25^{\circ}C \\ \end{array}$ 

Fig.7 Typical Stored Charge vs. dl<sub>F</sub>/dt (Per Leg)

800

0 100 dl<sub>F</sub>/dt - (A/s) 1000

Fig.8 Typical dI<sub>(rec)M</sub>/dt vs. dI<sub>F</sub>/dt (Per Leg)





Fig.9 Reverse Recovery Parameter Test Circuit



Fig.10 Reverse Recovery Waveform and Definitions





#### **ORDERING INFORMATION TABLE**



